	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1172	redistribution adj (assembly or layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	739055	dies or wafer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	1009	2 and (backside with coating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
4	IS&R	L4	1	("6570233").PN.	USPAT
5	IS&R	L5	7	(("5682065") or ("6709953") or ("6023094") or ("6368896") or ("6560122") or ("6462426") or ("6075290")).PN.	USPAT
6	IS&R	L6	237	(438/114).CCLS.	USPAT
7	BRS	L7	134	workpiece and (backside with coating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L8	0	("2005/0280164").URPN.	USPAT
9	BRS	L9	1	("2005/0085006").URPN.	USPAT
10	BRS	L10	220055	workpiece or wafer	USPAT
11	BRS	L11	1169	10 with back with coat$4	USPAT
12	BRS	L12	28	11 with flow$4	USPAT
13	BRS	L13	531523	workpiece or wafer	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
14	BRS	L14	44	13 with (back or backside) with coat$4 with flow$4	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
15	BRS	L15	19	10 with backside with coat$4 with flow$4	USPAT
16	BRS	L16	7195	flex adj circuit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
17	BRS	L17	1173	16 and (workpiece or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
18	BRS	L18	60	17 and ((back or backside) with coat$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB